

July 2013

FCPF260N60E_F152

N-Channel SuperFET[®] II MOSFET 600 V, 15 A, 260 m Ω

Features

- 650 V @T_J = 150°C
- Max. R_{DS(on)} = 260 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 48 nC)
- Low Effective Output Capacitance (Typ. C_{oss}.eff = 129 pF)
- 100% Avalanche Tested

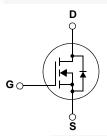
Aplications

- LCD / LED / PDP TV Lighting
- · Solar Inverter
- AC-DC Power Supply

Description

SuperFET[®]II MOSFET is Fairchild Semiconductor [®], s first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET[®]II MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter		FCPF260N60E_F152	Unit	
V _{DSS}	Drain to Source Voltage			600	V	
V	Cata ta Cauraa Valtaga	- DC		±20	V	
V_{GSS}	Gate to Source Voltage	- AC	(f > 1Hz)	±30	V	
	Drain Current	-Continuous (T _C = 25°C)		15*	Δ.	
I _D	Drain Current	-Continuous (T _C = 100°C)		9.5*	A	
I _{DM}	Drain Current	- Pulsed	(Note 1)	45*	Α	
E _{AS}	Single Pulsed Avalanche Ene	rgy	(Note 2)	292.5	mJ	
I _{AR}	Avalanche Current		(Note 1)	3.0	Α	
E _{AR}	Repetitive Avalanche Energy		(Note 1)	1.56	mJ	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns	
αν/αι	MOSFET dv/dt			100	V/IIS	
Б	Dower Discipation	$(T_C = 25^{\circ}C)$		36	W	
P_{D}	Power Dissipation	- Derate above 25°C		0.29	W/°C	
T _J , T _{STG}	Operating and Storage Temporal	erature Range		-55 to +150	°C	
TL	Maximum Lead Temperature 1/8" from Case for 5 Seconds	• .		300	°C	

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCPF260N60E_F152	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.5	
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink (Typical)	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Eco Status	Packaging Type	Quantity
FCPF260N60E	FCPF260N60E_F152	TO-220F	Green	Tube	50

For Fairchild's definition of "green" Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Prockdown Voltage	$V_{GS} = 0V, I_D = 10mA, T_J = 25^{\circ}C$	600	-	-	V
BV _{DSS} Drain to Source Breakdown Voltage	Dialii to Source Breakdown voltage	$V_{GS} = 0V, I_D = 10mA, T_J = 150^{\circ}C$	650	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10mA, Referenced to 25°C	-	0.67	-	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	V _{GS} = 0V, I _D = 15A	-	700	-	V
	Zoro Coto Voltogo Proin Current	$V_{DS} = 480V, V_{GS} = 0V$	-	-	10	
DSS	Zero Gate Voltage Drain Current	$V_{DS} = 480V, T_{C} = 125^{\circ}C$	-	-	10	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	3.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 7.5A$	-	0.22	0.26	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 20V, I_D = 7.5A$	-	15.5	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V/ 05V/ V/ 0V/	-	1880	2500	pF
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V$ f = 1MHz		1330	1770	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11VII 12	-	85	130	pF
C _{oss}	Output Capacitance	$V_{DS} = 380V, V_{GS} = 0V, f = 1MHz$	-	32	-	pF
Coss eff.	Effective Output Capacitance	$V_{DS} = 0V$ to 480V, $V_{GS} = 0V$	-	129	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	48	62	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 380V, I_{D} = 7.5A$	-	7.4	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10V (Note 4)	-	17	-	nC
ESR	Equivalent Series Resistance	f = 1MHz	-/	5.8	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	20	50	ns
t _r		$V_{DD} = 380V, I_D = 7.5A$	-	11	32	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_G = 4.7\Omega$	-	89	188	ns
t _f	Turn-Off Fall Time	(Note 4	-	13	36	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	15	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	45	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{SD} = 7.5A$	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 7.5A	-	270	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	3.6	-	μС

Notes:

- ${\bf 1.}\ {\bf Repetitive}\ {\bf Rating:}\ {\bf Pulse}\ {\bf width}\ {\bf limited}\ {\bf by}\ {\bf maximum}\ {\bf junction}\ {\bf temperature}$
- 2. $\rm I_{AS}$ = 3A, $\rm V_{DD}$ = 50V, $\rm R_{G}$ = 25 $\Omega,$ Starting $\rm T_{J}$ = 25°C
- 3. I_{SD} \leq 7.5A, di/dt \leq 200A/µs, V_{DD} \leq BV_DSS, Starting T_J = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

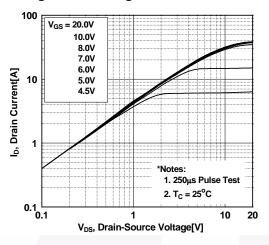


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

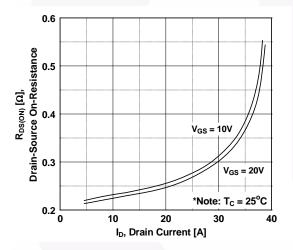


Figure 5. Capacitance Characteristics

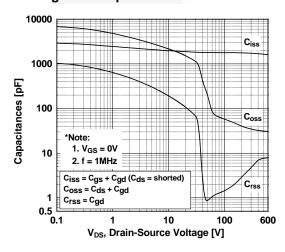


Figure 2. Transfer Characteristics

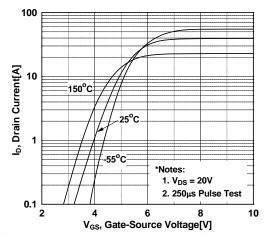


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

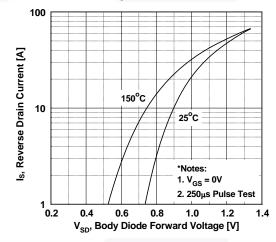
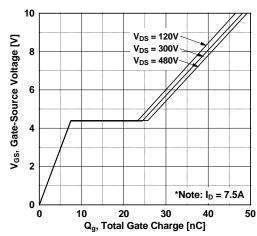


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

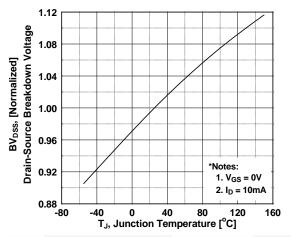


Figure 9. Maximum Safe Operating Area vs. Case Temperature

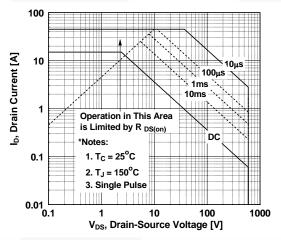


Figure 11. Maximum Drain Current

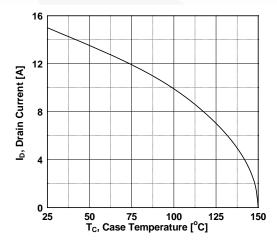


Figure 8. On-Resistance Variation vs. Temperature

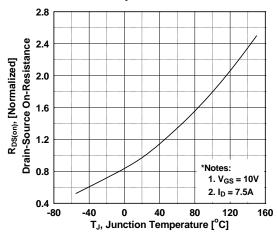
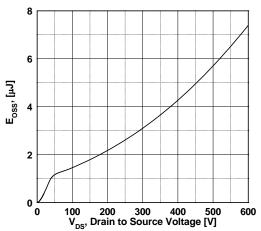
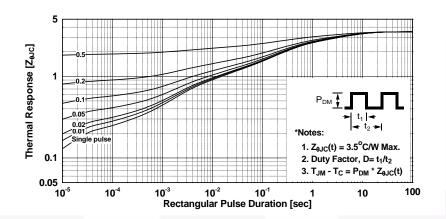


Figure 10. Eoss vs. Drain to Source Voltage Switching Capability

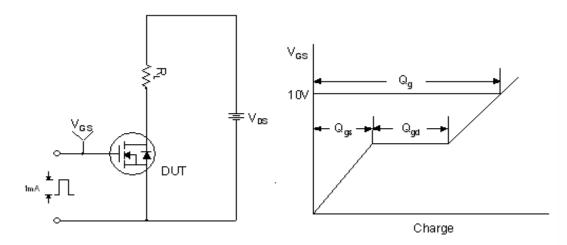


Typical Performance Characteristics (Continued)

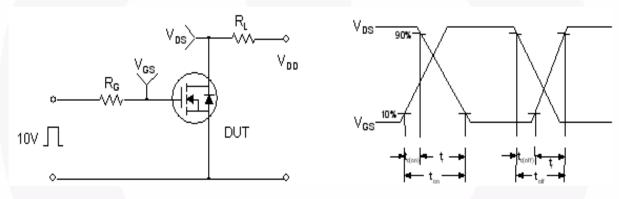
Figure 12. Transient Thermal Response Curve



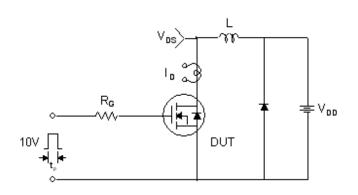
Gate Charge Test Circuit & Waveform

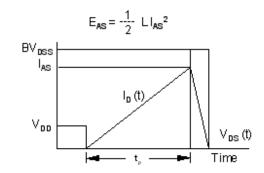


Resistive Switching Test Circuit & Waveforms

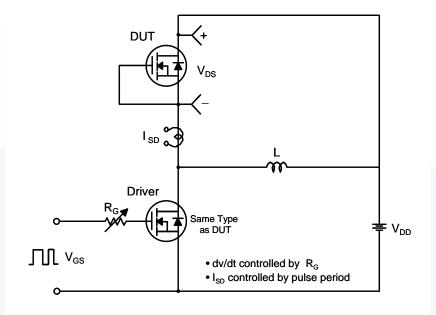


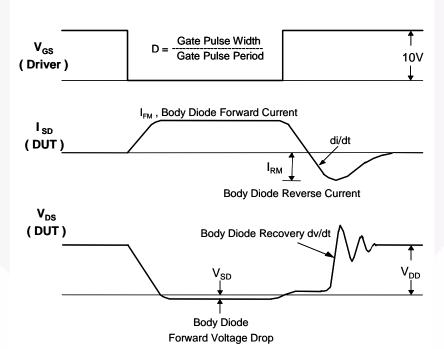
Unclamped Inductive Switching Test Circuit & Waveforms





Peak Diode Recovery dv/dt Test Circuit & Waveforms





Mechanical Dimensions TO-220F 10.30 A 9.80 2.90 Ø3.40 2.50 3.00 6.60 6.20 3.00 2.60 1 X 45° 19.00 15.70 17.70 15.00 3.30 B 3 2.70 (2.14) 2.30 1.20 0.90 (2X) 10.70 10.30 0.60 0.50 (3X) 1.20 0.50 M A 1.00 NOTES: 2.74 (2X)2.34 A. EXCEPT WHERE NOTED CONFORMS TO A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A. B. DOES NOT COMPLY EIAJ STD. VALUE. C. ALL DIMENSIONS ARE IN MILLIMETERS. D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS. mm mm 4.60 E. DIMENSION AND TOLERANCE AS PER ASME 4.30

* Front/Back Side Isolation Voltage : AC 2500V

F. DRAWING FILE NAME: TO220V03REV1

TO-220, MOLDED, 3LD, FULL PACK, EIAJ SC91

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